



## SMT10N60

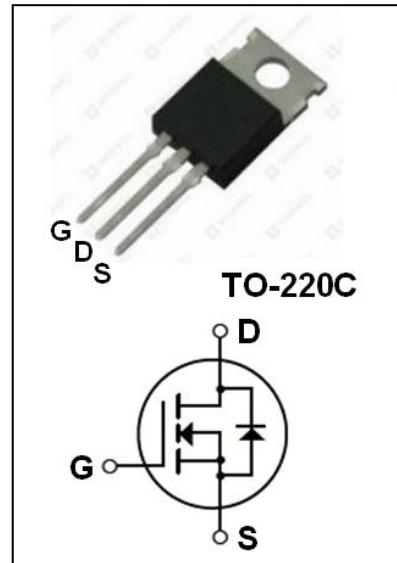
600V N-Channel MOSFET

### ● Features:

- 10.0A, 600V,  $R_{DS(on(Typ))} = 0.7\Omega$  @  $V_{GS} = 10V$
- Low Gate Charge
- Low  $C_{rss}$
- 100% Avalanche Tested
- Fast Switching
- Improved dv/dt Capability

### ● Application:

- High Frequency Switching Mode Power Supply
- Active Power Factor Correction



### Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit	
$V_{DSS}$	Drain-Source Voltage	600	V	
$I_D$	Drain Current - Continuous ( $T_c = 25^\circ C$ )	10.0*	A	
	- Continuous ( $T_c = 100^\circ C$ )	6.0*	A	
$I_{DM}$	Drain Current - Pulsed	(Note 1)	40*	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V	
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	713	mJ
$I_{AR}$	Avalanche Current	(Note 1)	10.0	A
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	17.8	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	(Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_c = 25^\circ C$ )	140	W	
	-Derate above $25^\circ C$	1.12	W/ $^\circ C$	
$T_j$	Operating Junction Temperature	150	$^\circ C$	
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ C$	

\* Drain Current Limited by Maximum Junction Temperature.

### Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.89	$^\circ C / W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	$^\circ C / W$

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**Electrical Characteristics(Tc=25°C unless otherwise noted)**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	600	--	--	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> =250μA (Referenced to 25°C)	--	0.7	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	--	--	1	μA
		V <sub>DS</sub> =480V, T <sub>c</sub> =125°C	--	--	10	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current,Forward	V <sub>GS</sub> =+30V, V <sub>DS</sub> =0V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current,Reverse	V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	--	4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10 V, I <sub>D</sub> =5.0A	--	0.7	0.95	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =40 V, I <sub>D</sub> =5.0A (Note4)	--	6.2	--	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	--	1132	--	pF
C <sub>oss</sub>	Output Capacitance		--	135	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	20	--	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 300 V, I <sub>D</sub> = 10 A, R <sub>G</sub> = 25 Ω (Note4,5)	--	33	--	ns
t <sub>r</sub>	Turn-On Rise Time		--	60	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	59	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	39	--	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 480 V, I <sub>D</sub> = 10 A, V <sub>GS</sub> = 10 V (Note4,5)	--	19.4	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	6.26	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	6.55	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current	--	--	10	--	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current	--	--	40	--	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =10.0A	--	--	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>S</sub> =10.0A, d I <sub>F</sub> /dt=100A/μs (Note4)	--	425	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	4.31	--	μC

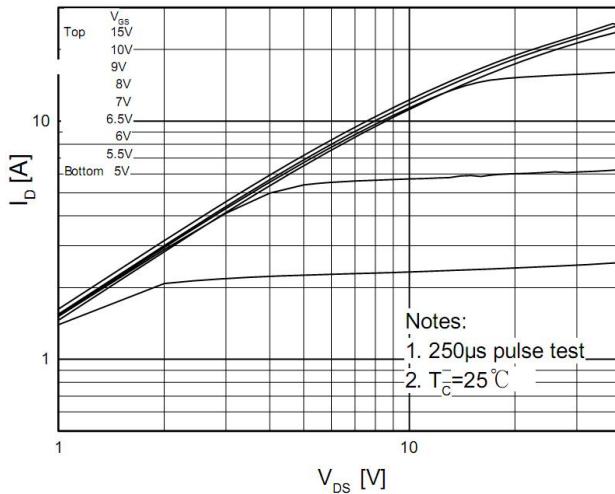
## Notes:

1. Repetitive Rating:Pulse Width Limited by Maximum Junction Temperature.
2. L = 14.5mH, I<sub>AS</sub> =10.0A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C.
3. I<sub>SD</sub>≤10.0A, di/dt≤200A/μs, V<sub>DD</sub>≤BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C.
4. Pulse Test : Pulse Width ≤300 μ s, Duty Cycles≤2%.
5. Essentially Independent of Operating Temperature.

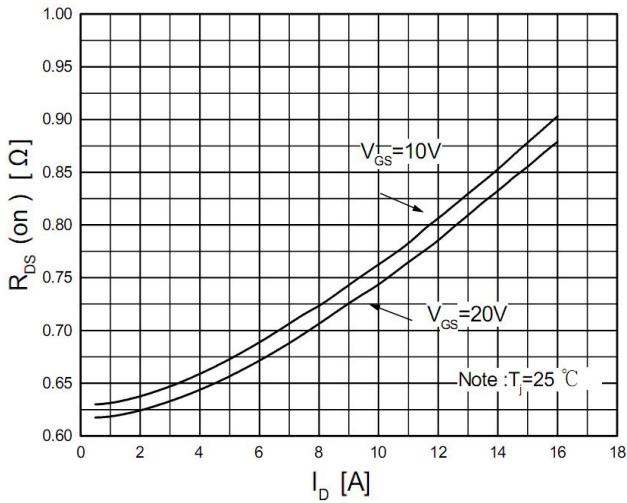
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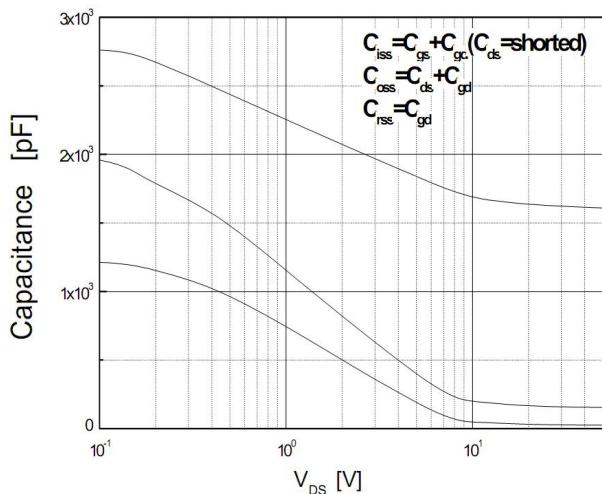
### On-Region Characteristics



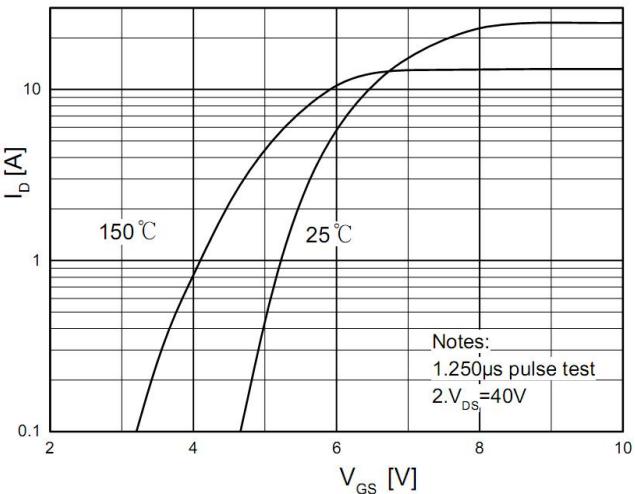
### On-Resistance Variation vs. Drain Current and Gate Voltage



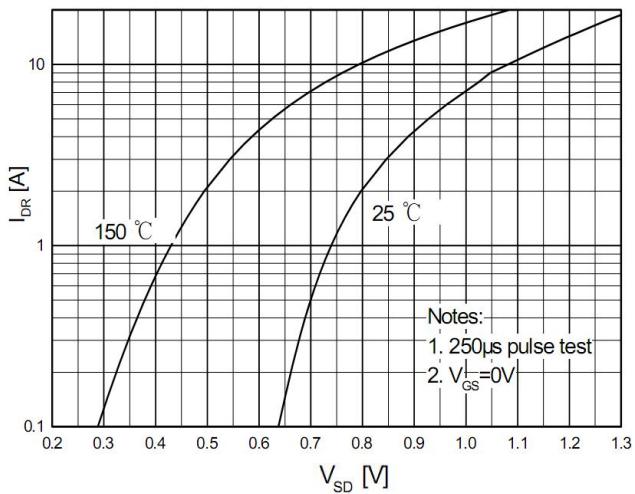
### Capacitance Characteristics



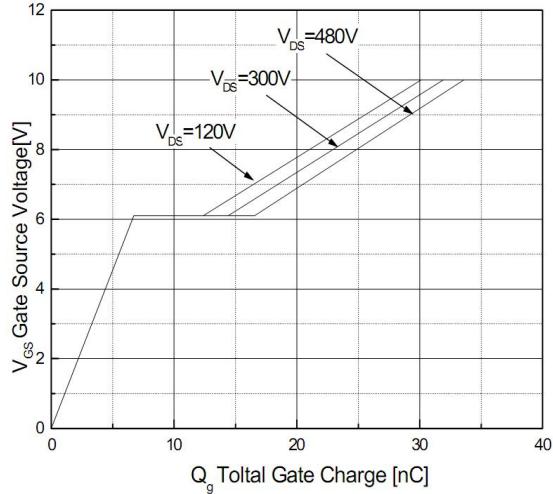
### Transfer Characteristics



### Body Diode Forward Voltage Variation vs. Source Current and Temperature



### Gate Charge Characteristics

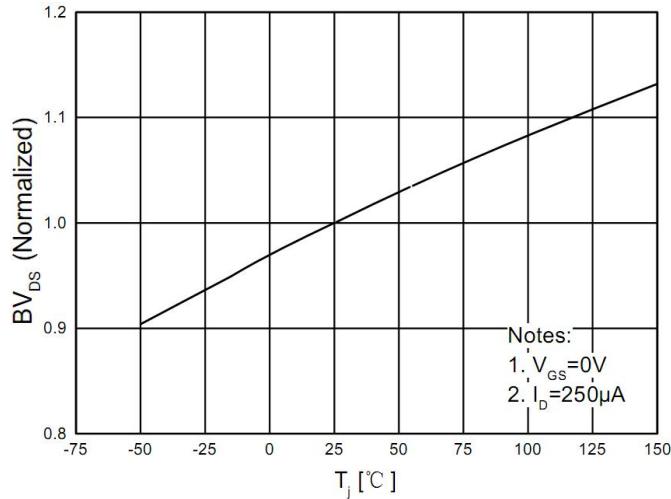




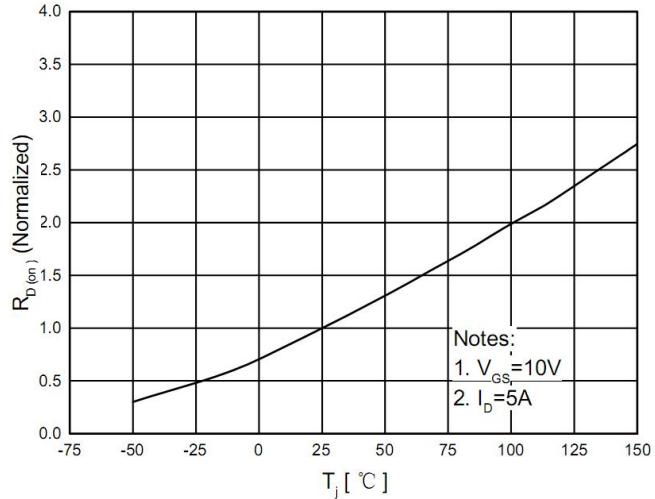
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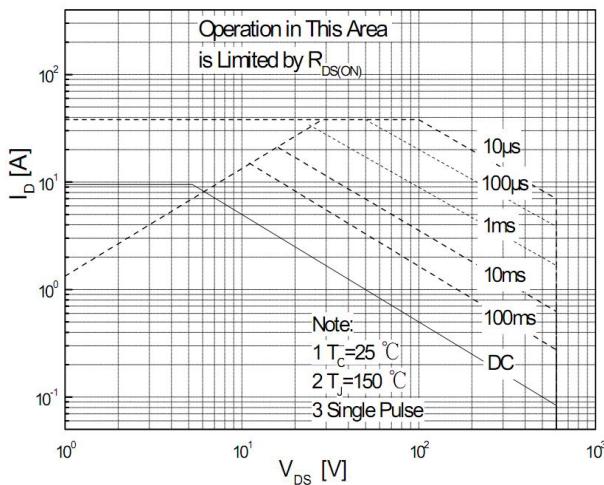
### Breakdown Voltage Variation vs. Temperature



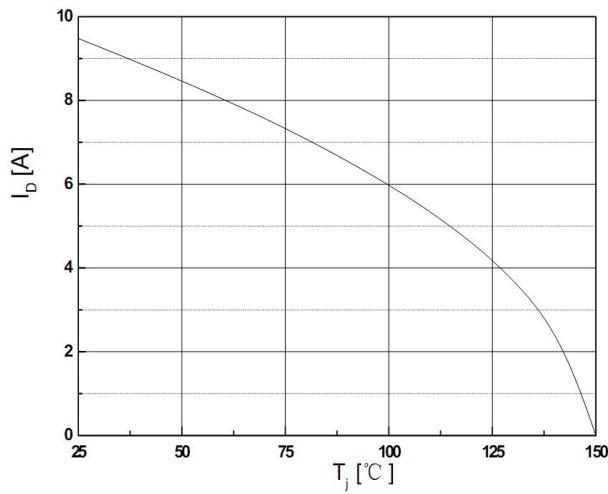
### On-Resistance Variation vs. Temperature



### Maximum Safe Operating Area



### Maximum Drain Current Vs. Case Temperature





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## TO-220 MECHANICAL DATA

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	4.00		4.80	E	9.50		10.50
B	1.25		1.55	e		2.54	
B1	0.55		1.05	F	1.15		1.45
b1	0.65		0.95	L	12.00		14.00
c	0.40		0.60	L1	2.50	3.00	3.50
D	14.80		16.80	Q	2.50		3.50
D1	6.00		7.00	Q1	1.80		2.80
				φ P	3.40		3.90

